



Product Specifications

Product No.: SCD-014

1) Rating: DC 30V 0.3A

2) Operating Temperature Range: $-10^{\circ}\text{C} \sim +60^{\circ}\text{C}$

3) Electrical Performance:

	Test Conditions	Performance		
Contact Resistance	Measured at small current (10mA	50mΩ Max.		
Contact Resistance	1000Hz or less)			
	Apply a voltage of 500V DC			
	shall be applied for 1 minute after			
	which measurement taken:			
	(1) Between terminals not to			
Insulation Resistance	be contact	100MO M:-		
	(2) Between body and	100MΩ Min.		
	terminal			
	(3) Between terminals not to			
	be contact when plug is			
	inserted			
Dielectric Strength	AC500V rms (50-60Hz) for 1			
	minute trip current: 0.5mA			
	(1) Between terminals not to			
	be contact.	Without damage to parts arcing or breakdown		
	(2) Between body and			
	terminal			
	(3) Between terminals not to			
	be contact when plug is			
	inserted.			

4) Mechanical Performance:

	Test Conditions	Performance	
Insertion Force	Measurement shall be made after 3 times of insertion and extraction with gauge plug	600~1500 gf	
Extraction Force	Measurement shall be made after 3 times of insertion and extraction with gauge plug	500~1500 gf	
Terminal Strength	A static load of 150gf shall be applied to the terminal for 15 seconds in any direction	Electrical characteristics shall be satisfied without damage or excessive looseness of terminals	
Life Test	Endurance without load: Jack shall be subjected to 5,000 cycles at a rate of 15 to 18 cycles per minute without loading.	 (1) Contact resistance: 100mΩ Max. (2) Insulation Resistance: 50MΩ Min. (3) Withstand Voltage: AC 500V 	



	(4)	for 1 minute. Without damage to parts
		arcing or breakdown.

5) Environmental Characteristics:

5) Environmental Chai	Test Conditions	Performance		
	The top of terminals shall be	The Area of soldering should be		
Solderability Test	dipped 2mm in the solder bath of	over 75%		
•	230±5°C for 3±0.5 seconds			
	Solder Bath method:			
	Solder temperature 230±5°C			
	Immersion Time 3±0.5 seconds			
	Immersion depth up to the			
	surface of the board 1.6mm	Without deformation of case or		
B 1	dimensions of component holes	excessive looseness of terminals		
Resistance to Solder Heat Test	in the printed wiring board shall	electrical characteristics shall be		
	be in accordance with those	satisfied.		
	specified in this document.			
	Solder iron method:			
	temperature of solder 350±10°C			
	time of solder 3±0.5 sec.			
	The jack shall be stored at a			
	temperature of -25± 3°C for 48			
	hours, then the switch shall be			
Cold Test	maintained at standard			
	atmospheric conditions for 1 hour			
	after which measurement shall be			
	made	There shall be no deformation or		
	The jack shall be stored at a	cracks in the molded part.		
	temperature of 70±2°C for 48			
	hours, then the jack shall be			
Heat Test	maintained at standard			
	atmospheric conditions for 1 hour			
	after which measurement shall be			
	made.			
	The jack shall be stored at a			
	temperature of 40±2°C and a			
	humidity of 90% to 98% for 48			
Humidity Test	hours, then the jack shall be	There shall be no deformation or		
	maintained at standard	cracks in molded part.		
	atmospheric conditions for 1 hour			
	after which measurement shall be			
Tr	made.	(A)		
Test Condition (Unless otherwise specified)				
Temperature: 5°C - 35°C Humidity: 45% - 85% R.H.				
Pressure: 86 – 106kPa				
11055uic. 00 – 100KFa				

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